LASICKT has been improved so that it can trace through a layout. Before (in older versions of LASICKT), the layers used for interconnection in a layout, see page 157, were specified but there was no way to have them interconnected. The result was significant labeling of nodes within the layout to show connections. Now a *Layer Trace Matrix* is used to specify how layers are interconnected. If the form.dbd file in the design directory contains the MOSIS setups then the layers can be specified as shown below. The first layers used for interconnect are poly1 (layer 46) and active (layer 43). These layers are not connected to each other. The contact layer (25) specifies cuts in the insulation. The next layer used for connections is Metal1 (layer 49), etc. So, looking at the table, Metal1 is connected to active and to poly1 through a contact. Metal1 is also connected to Metal2 (layer 51) through Via1 (layer 50). LASICKT will also specify parasitic capacitances based on the area of the interconnect.

Also, cells that are floating, that is, without any connectors, can now be smashed using the "smash table,". For the purposes of extracting a netlist using LASICKT the cells listed in the smash table are treated as if they were drawn in the cell that they are placed.

Layer Trace Matrix				Smash Table	
SURFACE	Layers	☐ Capacitance		Cellnames	
Conductor		0.	1	PAD	
Insulator			2	VIA	
Conductor	62	0.	3	CONTACT	
Insulator	61		4	SFRAME	
Conductor	51	0.	5		
Insulator	50		6		
Conductor	49	0.	7		
Insulator	25		8		
Conductor	46 43	0	9		
	OK	Cancel	10		
				OK	Cancel